ABSTRACT

AN IMPROVED BALL MOUNTING APPARATUS AND METHOD

A device for mounting an array of solder balls to a plurality of substrates of integrated circuits, comprising: a first plate for receiving a first substrate in a loading position; said first plate adapted to translate laterally from a substrate loading position to a flux receiving position; said first plate further adapted to rotate 180° from the substrate loading position to a such that the first plate is in a solder ball receiving position, and; mounting solder balls to the first plate.

FIGURE 2

